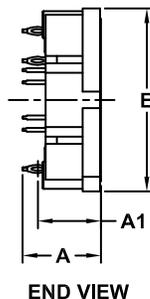
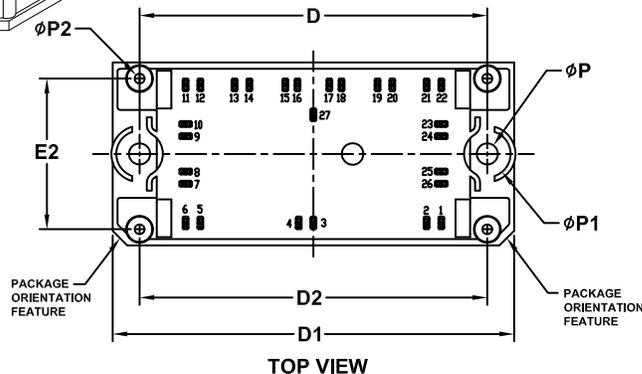
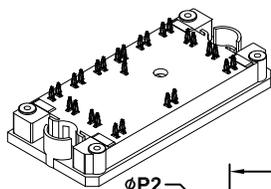
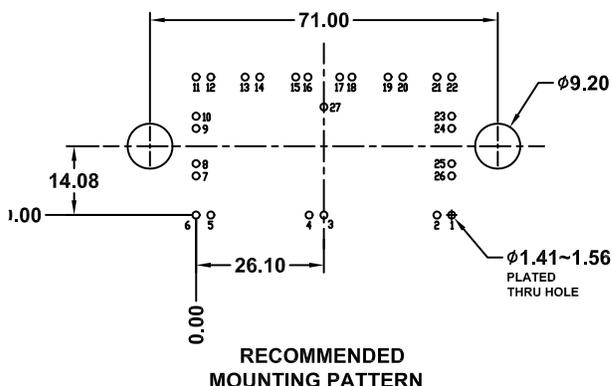
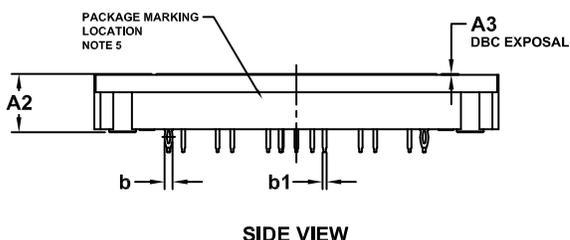


PIM27, 71x37.4 (PRESSFIT PIN)
CASE 180CP
ISSUE A

DATE 20 DEC 2022



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	15.50	16.00	16.50
A1	12.38	12.88	13.38
A2	11.70	11.90	12.10
A3	0.00	0.20	0.60
b	1.61	1.66	1.71
b1	0.75	0.80	0.85
D	70.80	71.00	71.20
D1	81.70	82.00	82.30
D2	70.80	71.00	71.20
E	37.10	37.40	37.70
E2	30.60	30.80	31.00
P	4.10	4.30	4.50
P1	9.30	9.50	9.70
P2	1.80	2.00	2.20



NOTE 4

PIN	PIN POSITION		PIN	PIN POSITION	
	X	Y		X	Y
1	52.20	0.00	15	20.35	28.20
2	49.20	0.00	16	22.85	28.20
3	26.10	0.00	17	29.35	28.20
4	23.10	0.00	18	31.85	28.20
5	3.00	0.00	19	39.20	28.20
6	0.00	0.00	20	42.20	28.20
7	0.00	8.00	21	49.20	28.20
8	0.00	10.50	22	52.20	28.20
9	0.00	17.70	23	52.20	20.20
10	0.00	20.20	24	52.20	17.70
11	0.00	28.20	25	52.20	10.50
12	3.00	28.20	26	52.20	8.00
13	10.00	28.20	27	26.10	22.10
14	13.00	28.20			

GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009
2. CONTROLLING DIMENSION : MILLIMETERS
3. DIMENSIONS b AND b1 APPLY TO THE PLATED TERMINALS AND ARE MEASURED AT DIMENSION A1
4. PIN POSITION TOLERANCE IS $\pm 0.4\text{mm}$
5. PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	PIM27, 71X37.4 (PRESSFIT PIN)	PAGE 1 OF 1

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